

ABSTRACT

A semiconductor device includes: a substrate; a semiconductor chip that is fixed to a first surface of the substrate; a chip covering lid body that is provided on the first
5 surface of the substrate so as to cover the semiconductor chip and that forms a hollow first space portion that surrounds the semiconductor chip, and in which there is provided a substantially cylindrical aperture portion that extends to the outer side of the first space portion and has an aperture end at a distal end thereof and that is connected to the first space portion; and a first resin mold portion that forms the first space portion via the chip
10 covering lid body and covers the substrate such that the aperture end is exposed, and that fixes the substrate integrally with the chip covering lid body.